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(54) Title: APPARATUS FOR PROCESSING A WAFER-SHAPED ARTICLE AND GRIPPING PIN

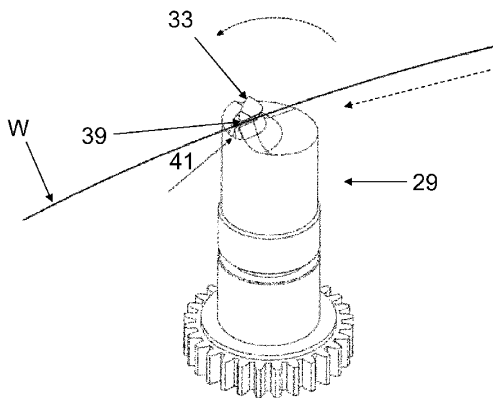


Fig. 13

(57) Abstract: An apparatus for processing a wafer-shaped article, comprising: a rotary chuck having a plurality of gripping pins adapted to hold a wafer-shaped article on the rotary chuck, wherein each of the plurality of gripping pins comprises a cylindrical body and a projecting gripping portion, wherein the projecting gripping portion comprises a first face configured to contact the wafer-shaped article and a second face, and wherein an angle of greater than or equal to 10 degrees and less than or equal to 70 degrees is formed between the first face and the second face at an edge of the projecting gripping portion.

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